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Ingenic 君正

Ingenic Semiconductor Co., Ltd.
北京君正集成電路股份有限公司

(A joint stock company incorporated in the People's Republic of China with limited liability)

(Stock Code: 3223)

AMENDMENTS TO THE ARTICLES OF ASSOCIATION

This announcement is made by Ingenic Semiconductor Co., Ltd. (the "**Company**") pursuant to Rule 13.51(1) of the Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited.

On August 25, 2026, a total of 31,287,300 H shares of the Company (the "**H Shares**") were issued and listed on The Stock Exchange of Hong Kong Limited (the "**Hong Kong Stock Exchange**"). As a result, the total number of issued shares of the Company increased to 514,951,667 shares, and the registered capital of the Company increased to RMB514,951,667.

To reflect the aforesaid changes in the registered capital and capital structure of the Company, pursuant to the authorization granted by the shareholders of the Company to the board (the "**Board**") of directors (the "**Directors**") of the Company at the general meeting held on September 11, 2025, the Board has approved to make corresponding amendments and housekeeping adjustments to the articles of association of the Company (the "**Articles of Association**"), details of which are set out below:

Before amendment:	**After amendment:**
Article 3 The Company completed the filing with the CSRC on June 22, 2026 and received the approval from The Stock Exchange of Hong Kong Limited (hereinafter referred to as the "Hong Kong Stock Exchange") on [•] for the initial public offering of [•] overseas listed foreign shares, and was listed on the Main Board of the Hong Kong Stock Exchange on [•].	**Article 3** The Company completed the filing with the CSRC on June 22, 2026 and received the approval from The Stock Exchange of Hong Kong Limited (hereinafter referred to as the "Hong Kong Stock Exchange") on **August 24, 2026** for the initial public offering of **31,287,300** overseas listed foreign shares, and was listed on the Main Board of the Hong Kong Stock Exchange on **August 25, 2026**.

Before amendment:	After amendment:
Article 6 The registered capital of the Company is RMB[•].	**Article 6** The registered capital of the Company is RMB**514,951,667**.
Article 21 The Company had issued [•] shares, comprising [•] ordinary shares (including 483,664,367 ordinary A Shares and [•] ordinary H Shares), with no shares of other classes.	**Article 21** The Company had issued **514,951,667** shares, comprising **514,951,667** ordinary shares (including 483,664,367 ordinary A Shares and **31,287,300** ordinary H Shares), with no shares of other classes.
Article 209 The Articles of Association shall be interpreted by the Board of the Company, and shall become effective and implemented from the date on which the H Shares issued by the Company are listed on The Stock Exchange of Hong Kong Limited after being considered and approved at the general meeting.	**Article 209 The Articles of Association shall be interpreted by the Board of the Company, and shall become effective and implemented ~~from the date on which the H Shares issued by the Company are listed on The Stock Exchange of Hong Kong Limited~~ after being considered and approved at the general meeting.**

Save for the aforesaid amendments and adjustments, all other provisions of the Articles of Association remain in full force and effect. The aforesaid amendments and adjustments are not subject to further consideration or approval by the general meeting of the Company.

The Company will complete the industrial and commercial registration, filing and other relevant procedures with the relevant government or regulatory authorities in respect of the aforesaid amendments and adjustments to the Articles of Association. The full text of the amended Articles of Association is available on the website of the Hong Kong Stock Exchange (www.hkexnews.hk) and the website of the Company (www.ingenic.com.cn).

By order of the Board
Ingenic Semiconductor Co., Ltd.
Dr. Liu Qiang
Executive Director, Chairman of the Board and General Manager

Beijing, the PRC, October 27, 2026

As of the date of this announcement, the Board comprises (i) Dr. Liu Qiang, Mr. Zhang Jin, Mr. Xian Yonghui and Mr. Huang Lei as executive Directors; (ii) Mr. Li Jie, Mr. Zheng Hao and Ms. Zhang Yanxiang as non-executive Directors; and (iii) Mr. Ye Jinfu, Dr. Xiao Limin, Ms. Yu Ying and Mr. Xiang Zuo as independent non-executive Directors.